



University of Glasgow | Department of  
Physics & Astronomy

# UK Advanced Instrumentation Training

## PCB Layout

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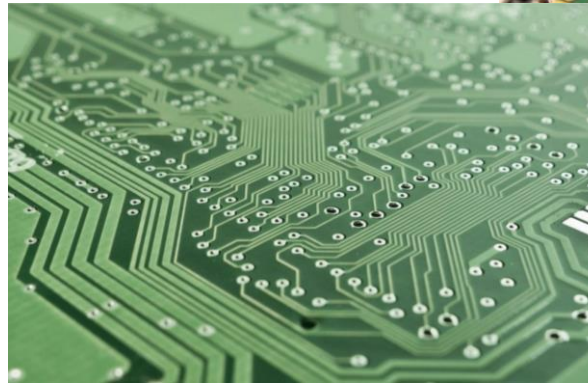
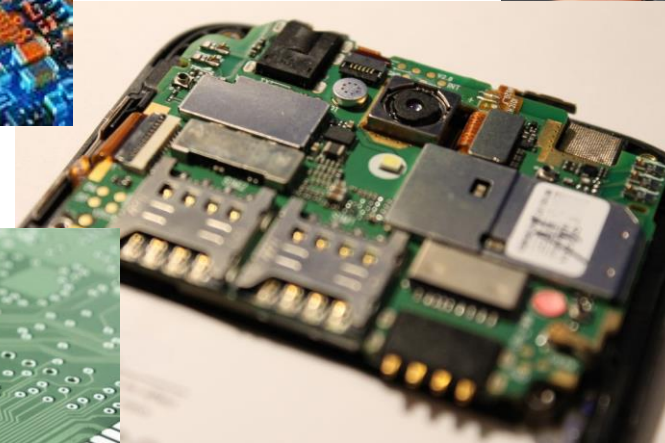
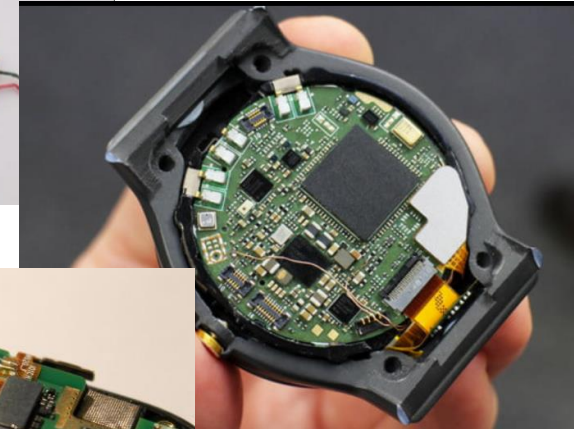
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# What is a Printed Circuit Board (PCB)

- A printed circuit board (PCB) is present in electronic devices, ranging from smartphones to home appliances. It is an electronic assembly that uses copper conductors to create electrical connections between components.
- It provides mechanical support for electronic components so that a device can be mounted in an enclosure.
- It can be rigid, flex, rigid-flex hybrid and the thickness can range from a few millimeter to a few microns based on technology.



# PCB design process

**Schematic  
design and  
creating a  
netlist**

**Setting the  
PCB design  
environment**

**PCB layout**

**Generating  
manufacturing  
data**

**Submitting  
files for  
fabrication**

**Quality  
control  
(QC)**

# Schematic design and creating a netlist

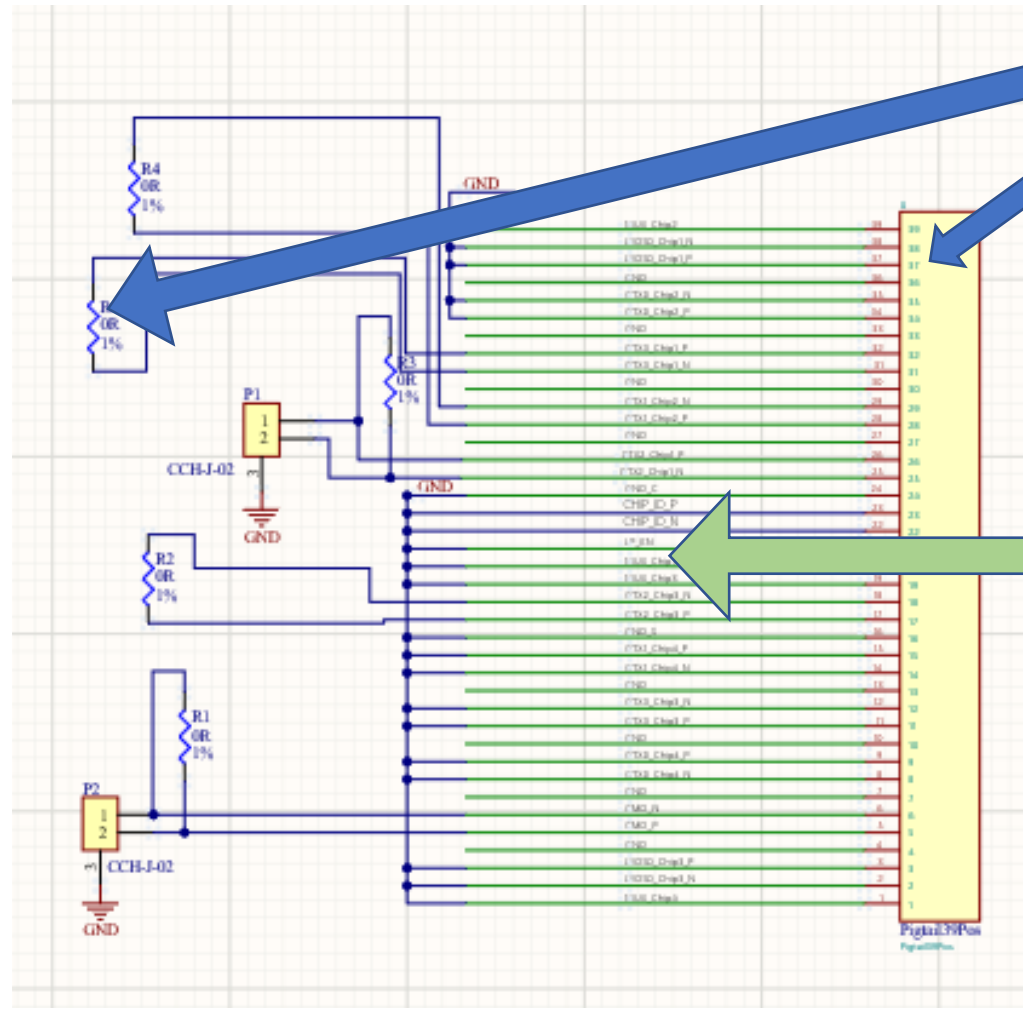
**Defines the circuit with symbols and nets**

**Creating symbols and footprints**  
**Associating symbols and footprints**

**Creating rules for critical nets**

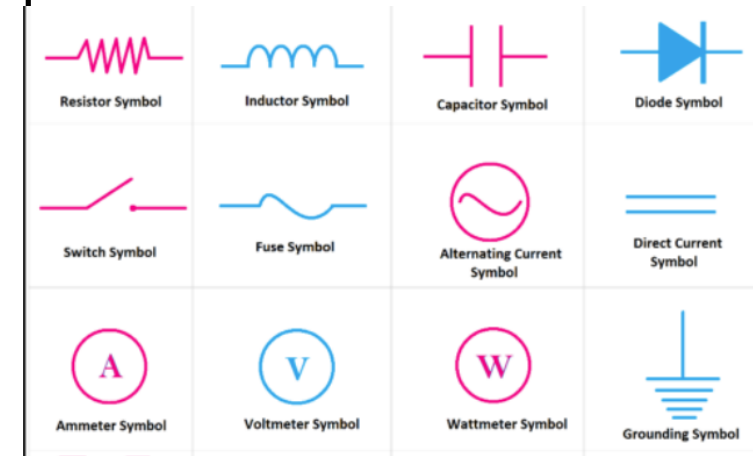
**Creating a netlist**  
**Netlist is a description of the connectivity of the circuit.**  
**Describes each component and its connections**

# Schematic design



• Schematic comprises of –

• Symbols



• Nets (connections)

- Design Rules are rules added to the schematic like no duplicate reference designator, floating net labels etc.
- Design Validation highlight the errors /warnings based on the defined rules.

# Setting the PCB environment

Layer  
stackup and  
design rules

PCB  
configuration

PCB  
composition

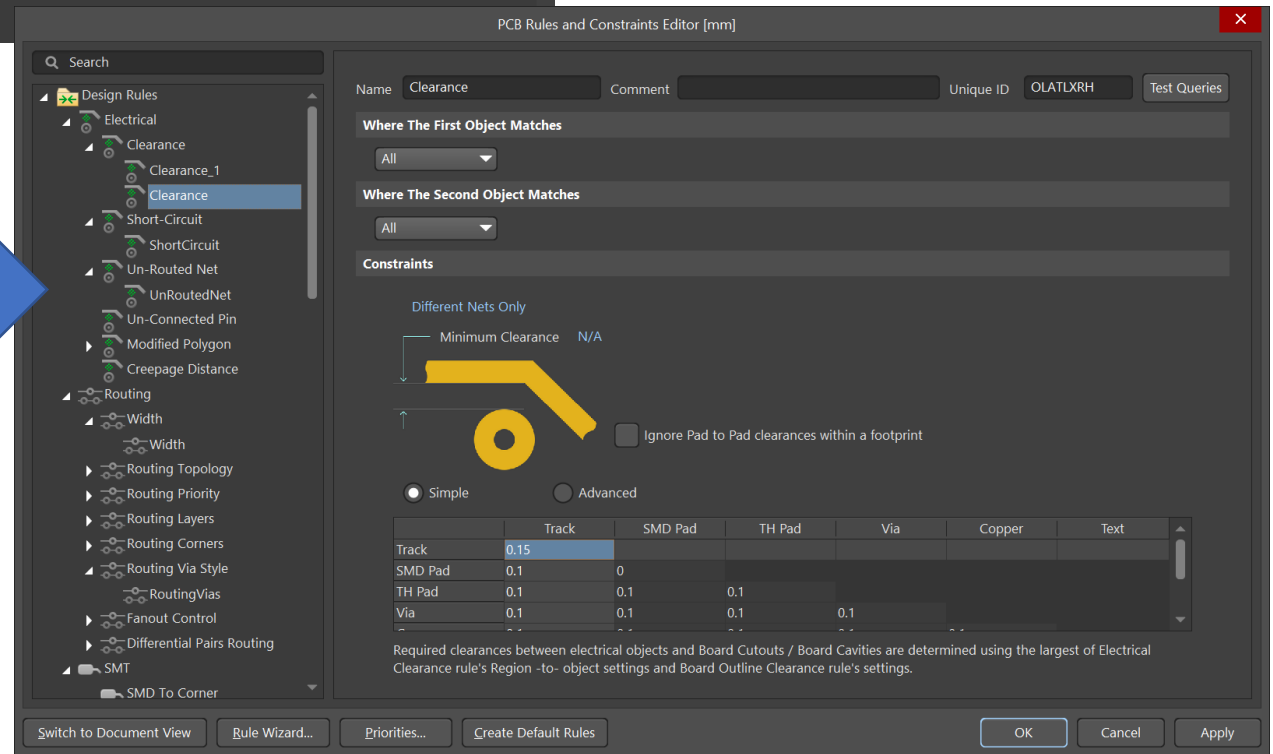
# Layer Stackup and design rules

#	Name	Material	Type	Thickness	Dk	Weight	Df
	F.Silks		Overlay				
	F.Mask	SM-001	Solder Mask	0.03mm	4		0.03
	Top Surface Finish	Nickel, Gold	Surface Finish	0.005mm			
1	F.Cu	CF-003	Signal	0.02mm		1/2oz	
	Dielectric 1	Core-006	Core	0.075mm	3.2		0.002
2	In1.Cu		Signal	0.009mm		1/2oz	
	Dielectric2	PP-001	Prepreg	0.03875mm	3.2		0.002
3	B.Cu	CF-003	Signal	0.02mm		1/2oz	
	Bottom Solder	SM-001	Solder Mask	0.05mm	4		0.03

- Define how many layers the PCB design would include.
  - Single sided, double sided or multilayer
  - Rigid, flex, rigid-flex

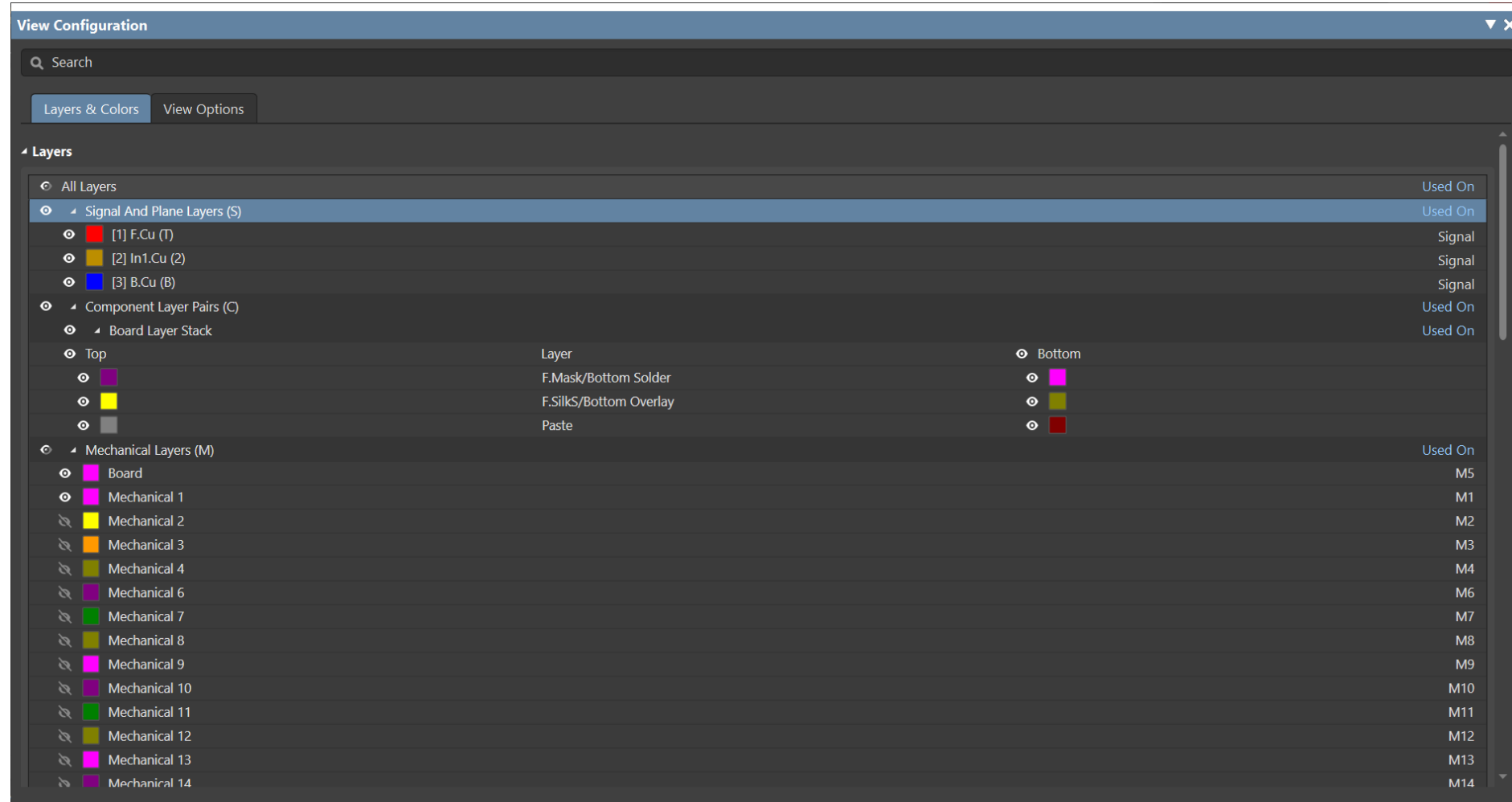
- Define design rules

- Clearance from traces to pads
- Min/max hole size
- Clearance of Cu from edge of the PCB
- Routing layers, routing topology
- Via geometry, etc.



# PCB configuration

- Layer stack definition reflects in the configuration window.
- Here the colours for the individual layers can be changed
- The layers can be turned on and on as required.
- Additional mechanical layers are available that can be used to add board outlines, DXFs etc.

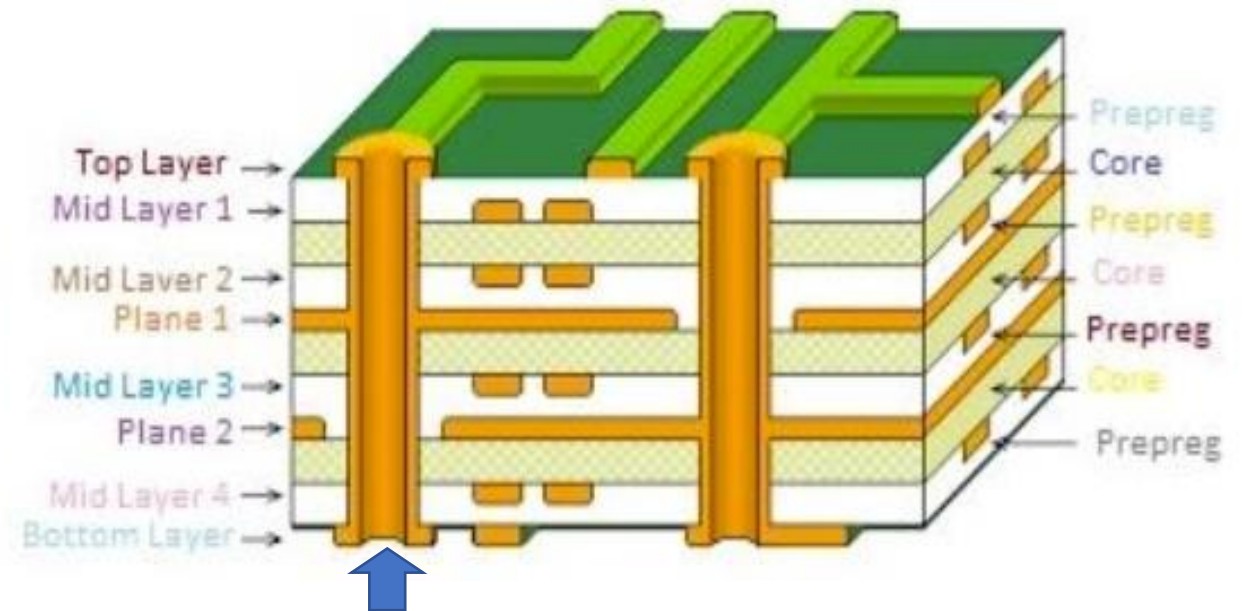
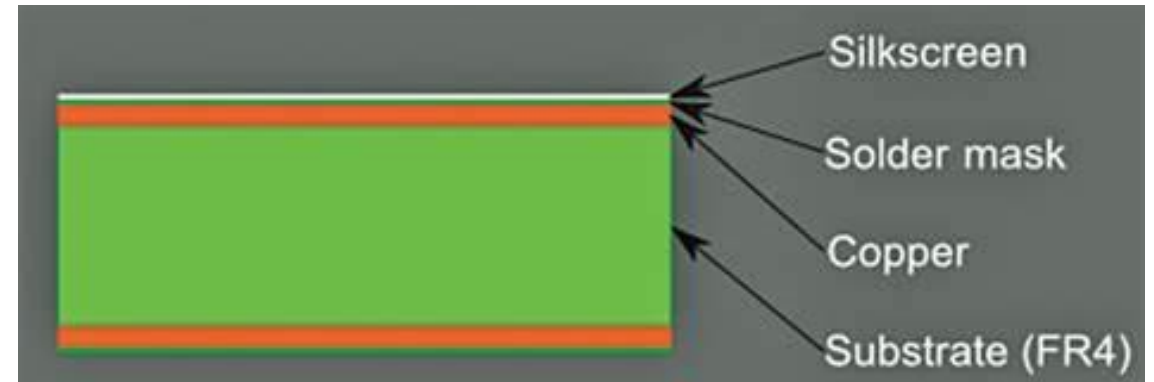




# PCB composition

## Different layers that make up a PCB

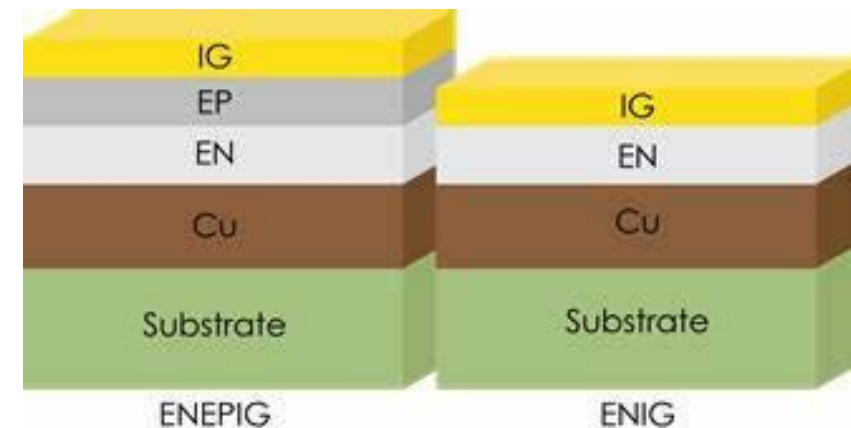
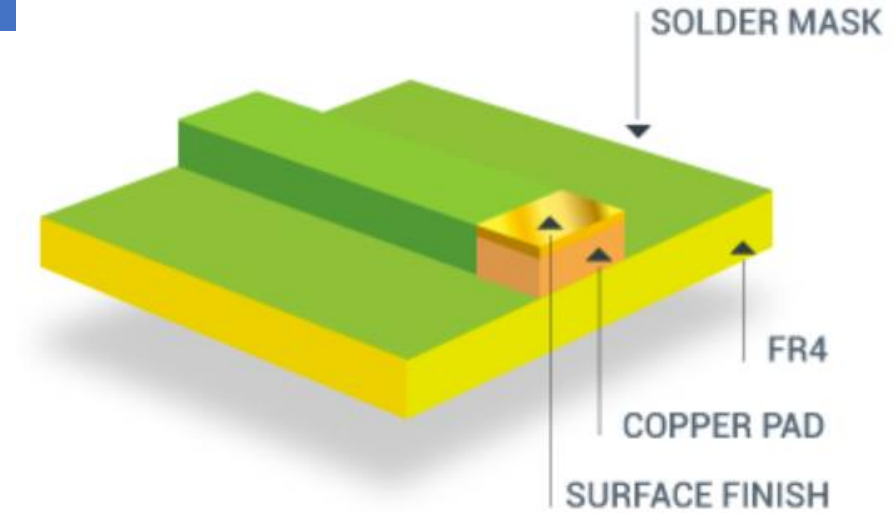
- Copper foil
- Substrate (FR4, Polyamide)
- Solder mask
  - Protect the copper from oxidation and shorts during operation.
- Silkscreen
  - Ink trace used to identify the PCB components, marks, logos, symbols
- Paste mask
  - Data for creating stencil for assembly of surface mount components



**Via** -consists of two pads in corresponding positions on different layers of the board, that are electrically connected by a hole through the board

# PCB surface finishes

- The purpose of surface finish
  - Prevent the copper from oxidizing
  - Provide a solderable surface.
- **Types of surface finish**
  - Hot Air Solder Leveling (HASL)
  - Organic Solderability Preservative (OSP)
  - Electroless Nickel Immersion Gold (ENIG)
    - This finish provides a thin, gold, solderable layer that protects the copper traces with a nickel barrier between it and the copper. ENIG is a good lead-free option that results in a durable, long-lasting finish.
    - Suitable for Aluminum wedge wirebonding
  - Electroless Nickel Immersion Palladium Immersion Gold (ENIPEG)
    - Ideal for gold wirebonding
    - Addresses the Black Pad (the corrosion of underlying nickel) issue.



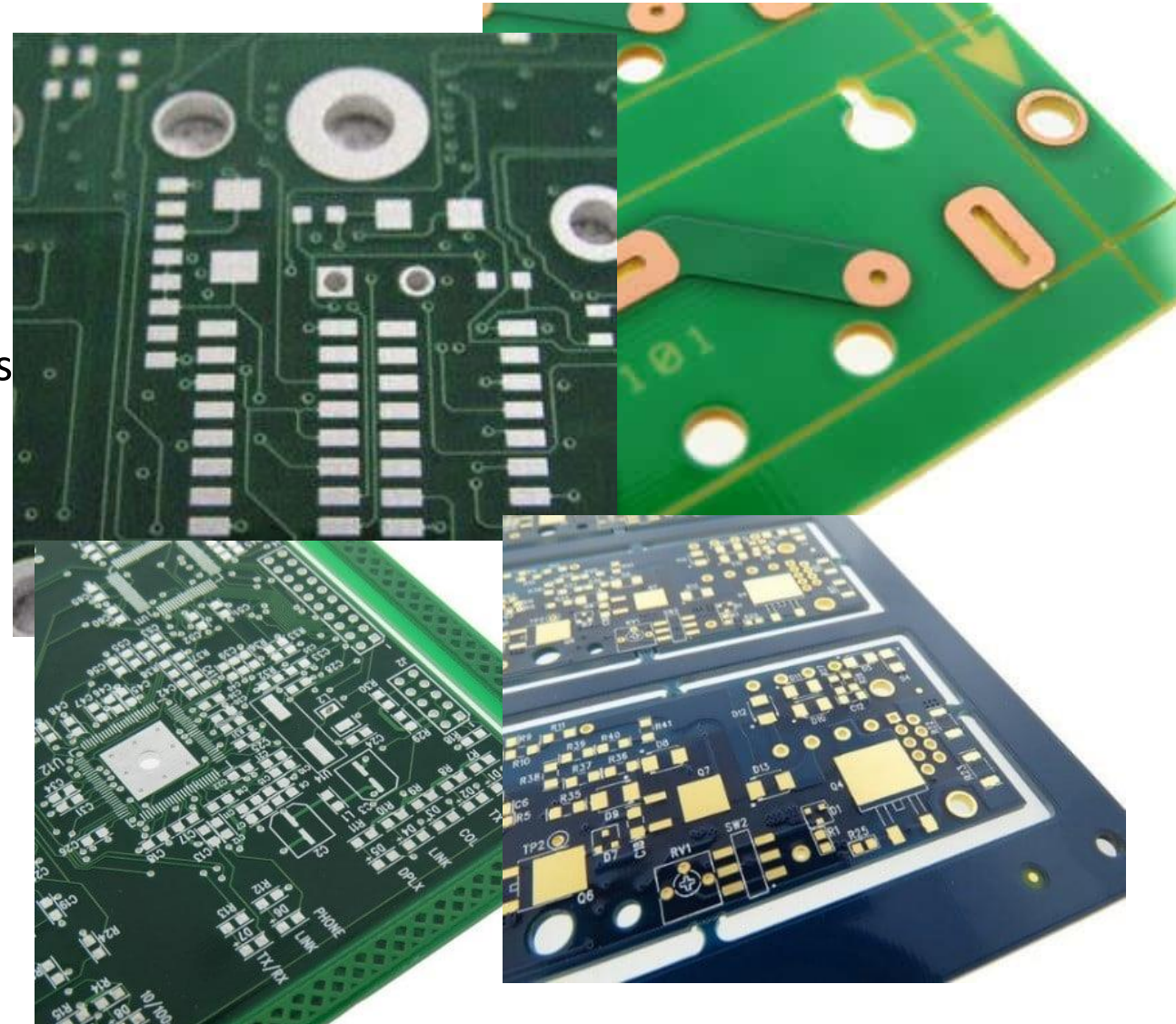
# PCB surface finishes

## Key Considerations When Choosing Your PCB Finish

- Price
- Availability
- Shelf life
- Reliability
- Assembly process
- Compliances like Restriction of Hazardous Substances (RoHS)

## Examples:

- If you do not need to be RoHS, Sn/Pb HASL may be your best option. It is low in cost and widely available.
- If your boards need to be RoHS and have fine pitch components including BGA's it is recommended to use ENIG or immersion silver.



# PCB layout

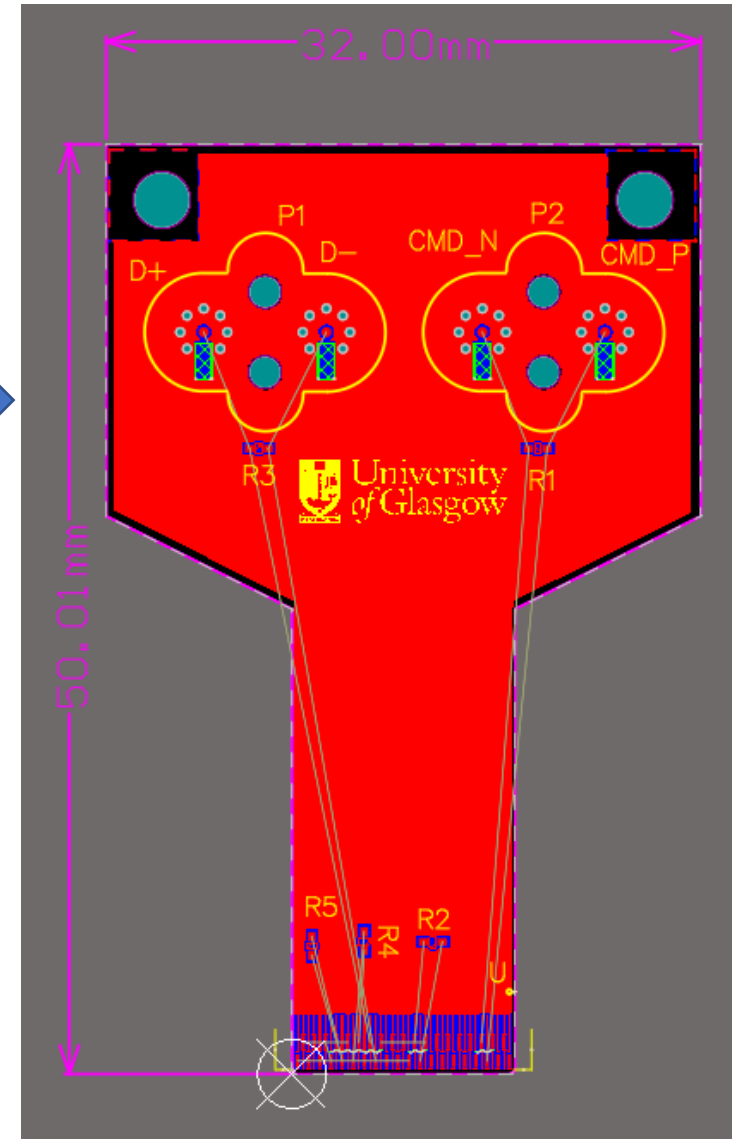
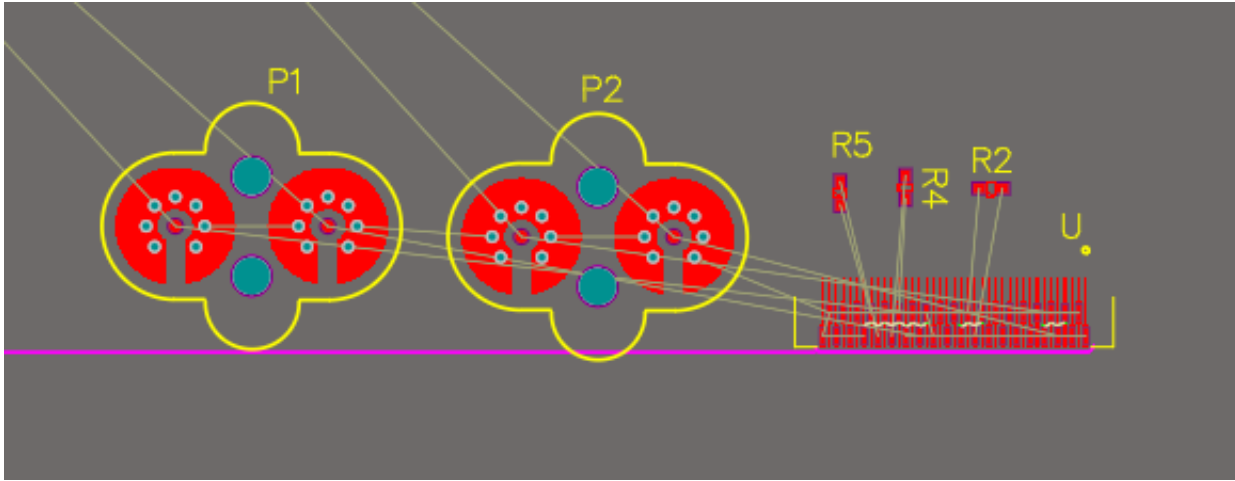
Placement of  
components

Define routing  
strategy, layout  
guideline, signal  
integrity etc.

Routing and  
design rule  
check

Mechanical  
considerations

# Placement of components

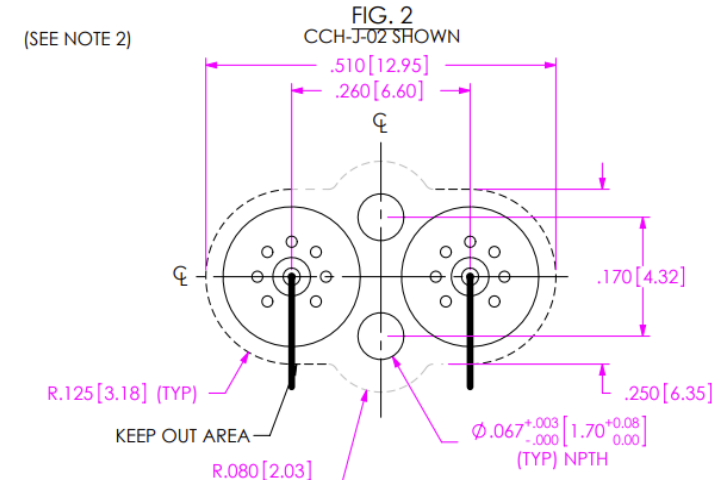
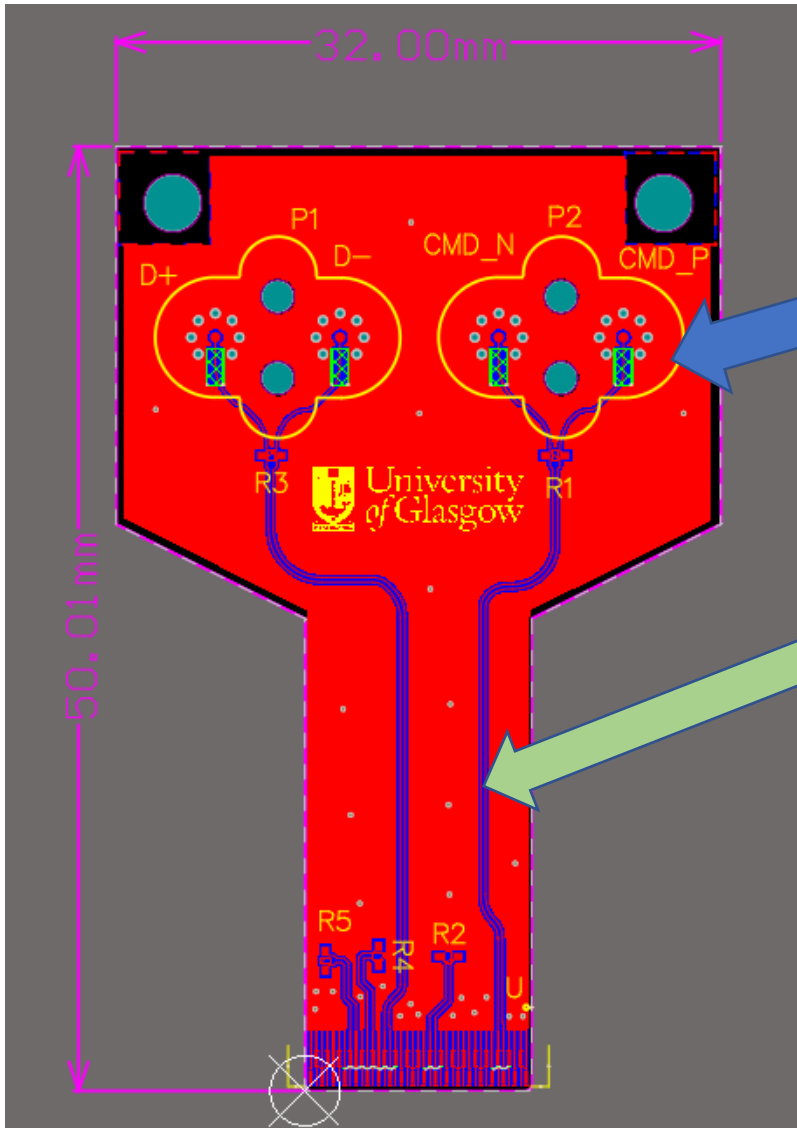


- Import design from schematic to bring the associated footprints and nets into the PCB file.
- There are libraries for symbols (schematic library) and for footprints (PCB library)
- Mechanical requirements shall be considered to define the shape and size of the PCB. This includes mechanical hole positions, sizes as well as cutouts.
- Footprints can then be placed on the PCB considering routing strategy.

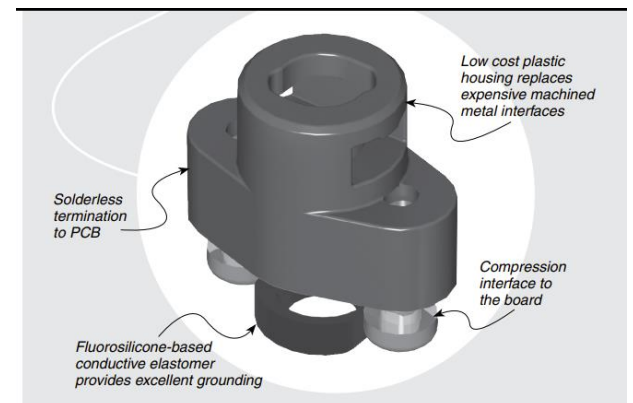


# Routing and design rule check (DRC)

- In the PCB layout –
  - The Symbols translate to footprints
  - The footprint is drawn to specifications as specified in the datasheet of the component.
- Nets translate to traces
- Rules and constraints
  - These are added to the design rules as per requirement of the design.
- Design rule check
  - This will highlight errors based on the set design rules.



## Information from the datasheet



# PCB Layout considerations

- **Board Constraints**

- Estimate the size and shape of the board
- Work around the mechanical requirements to fit the circuit.
- Define the number of layers required

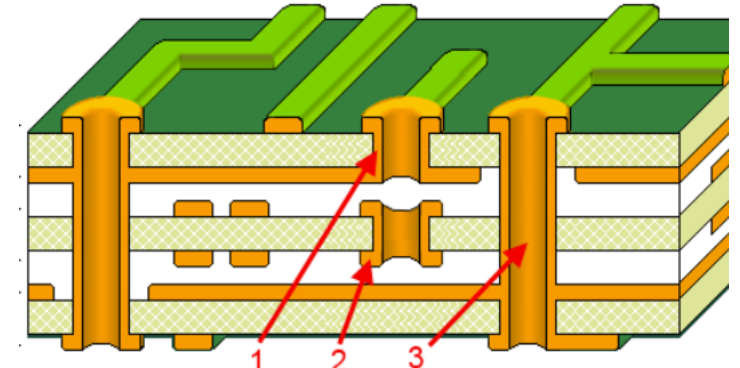
- **Manufacturing process/technology**

- Surface mounted/through hole blind and buried vias (high density interconnect (HDI))

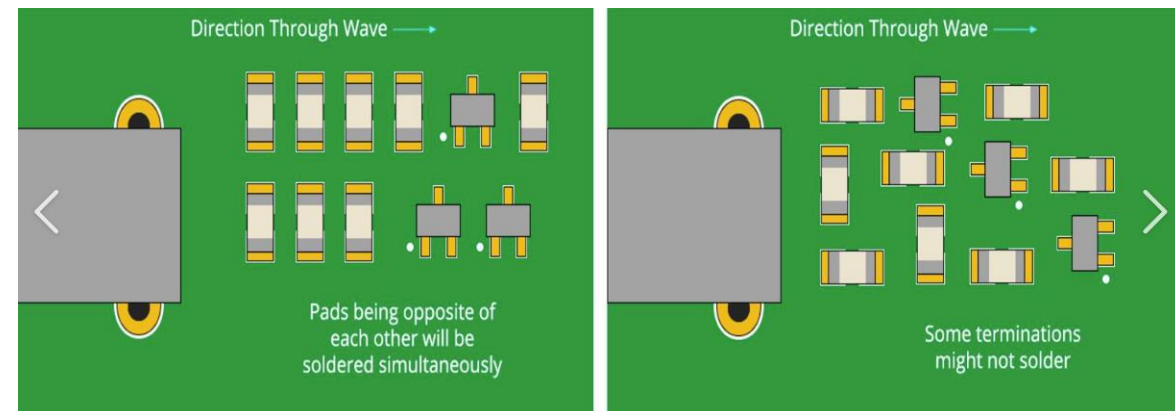
- **Placement and routing priorities**

- Placement sequence: Interconnects ->Power circuit ->High speed/critical circuits ->non-critical parts.
- Orientation of components to ease assembly
  - Place passives in one direction to the extent possible.

- **Single sided/Double sided/multilayer PCB**



1- Blind via; 2- Buried via; 3 -Through via



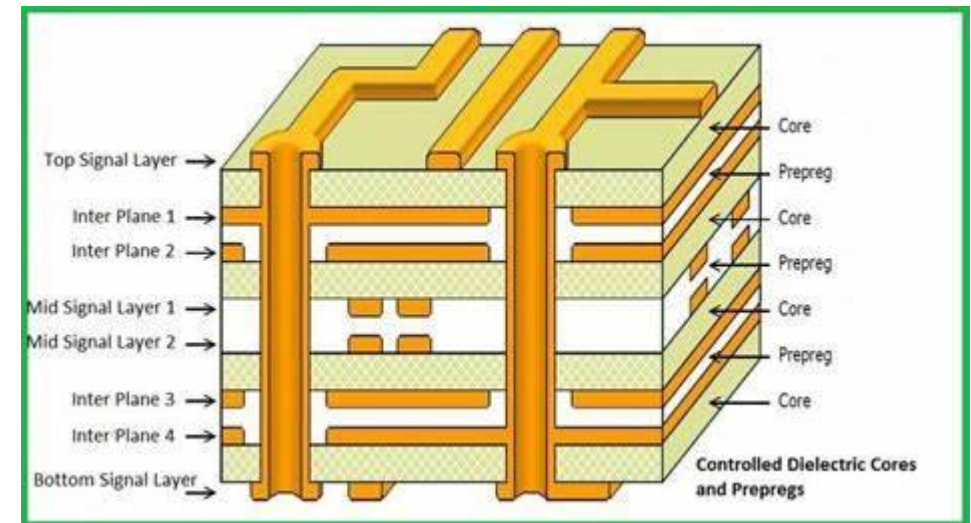
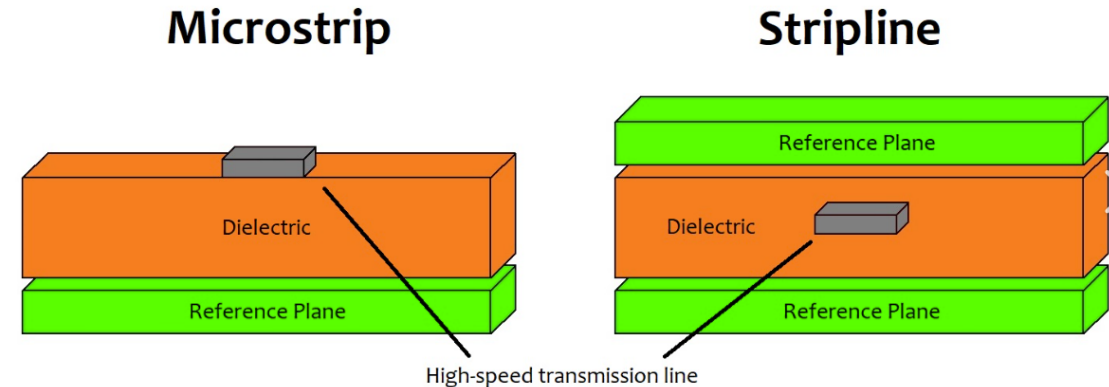
# PCB Layout considerations

- **Routing signals on PCB**

- Signals can be routed as Microstrip or Stripline
  - Microstrip or Stripline are transmission line structures on PCB
  - Signals in Microstrip move faster but are more prone to noise
  - Signals in Stripline have a more influence of the dielectric surrounding it but are more shielded.
- Defining layer stackup is important to ensure the signal routing technique is defined
  - Signal and plane layers based on density of the components and routing.
- Critical signals should be routed with a continuous GND reference to ensure controlled impedance of the trace.

- **Power and ground planes**

- Keep the power and ground planes internally in the PCB stackup.
- Ideally planes should be centered and symmetrical to prevent bowing and twisting of the PCB
- Keep the analog and digital grounds, power grounds separate.



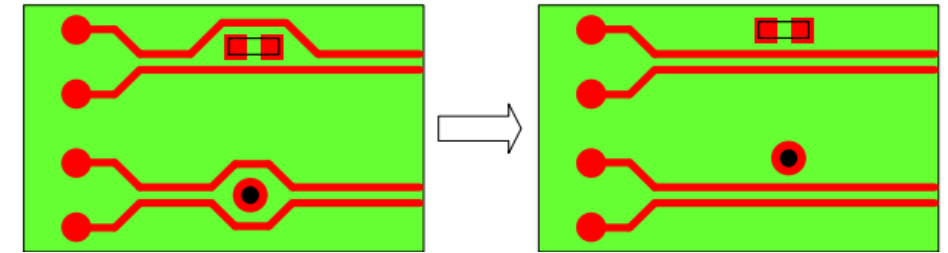
# PCB Layout considerations

- **Trace widths/trace spacings/ Via geometry**

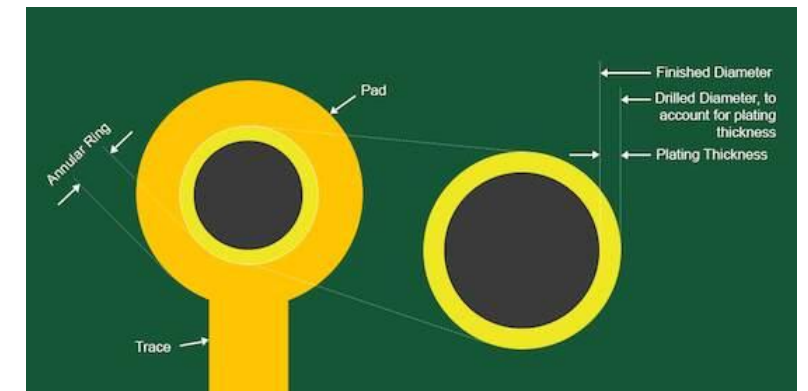
- Ensure that the specifications are such that the PCBs can be readily manufactured in industry.
- Design to meet the impedance requirement for high-speed signals (transmission lines at high speed).
- Keep critical signals well spaced from fast switching signals.
- Check via geometry meets thermal requirement

- **Signal Integrity**

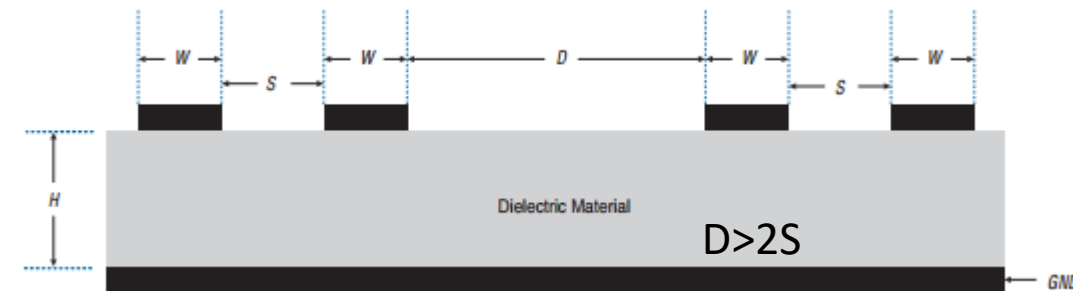
- Avoid large loops of signal and ground-return lines that carry high frequencies.
- Ensure continuous ground reference for critical signals
- Try using differential signaling scheme that is less prone to crosstalk
- Eliminate antennas, which can radiate electromagnetic energy
- Reduce trace stubs, reduce vias, terminate traces with termination resistors.
- Choose material suitable for high-speed signal transmission



Routing technique



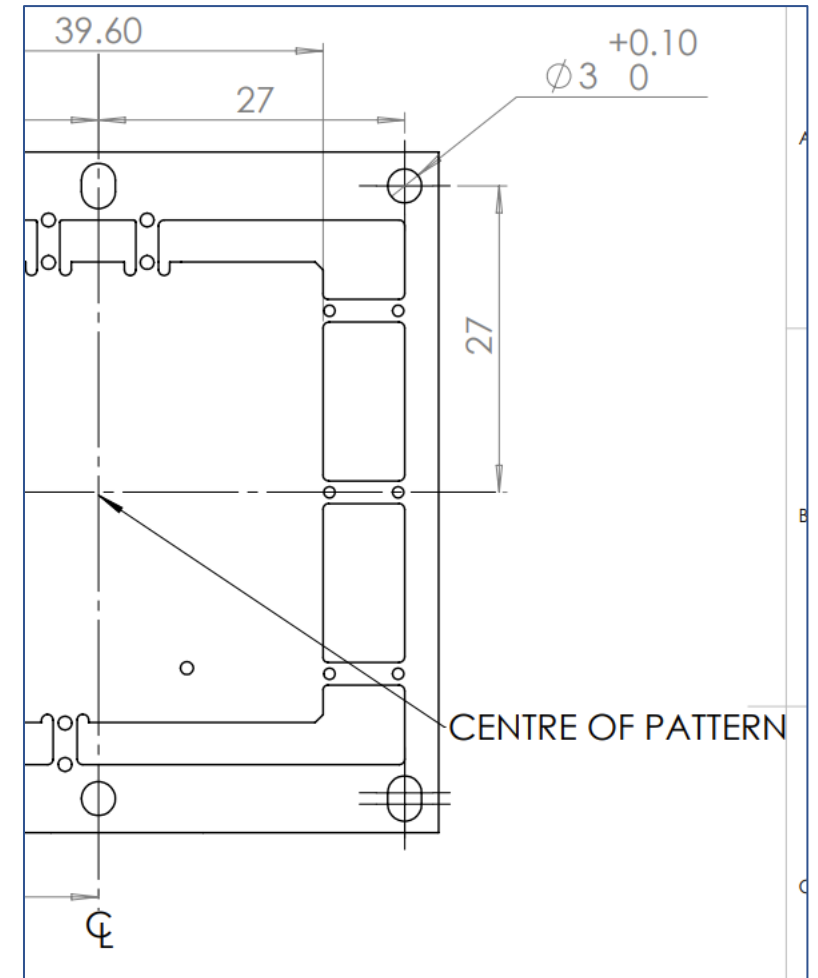
Via definition



Clearance rules to avoid crosstalk

# Mechanical Considerations

- Every PCB layout would have some mechanical requirements on allowed dimensions, thickness, allowed components heights, envelop etc.
- It is a critical step to liaise with mechanical team to understand these requirement and add these as constraints to the PCB layout.
- DXF/DWG files are a good way to share the design details between mechanical and electronics design.
- After the layout is complete, a final DXF is shared with the mechanical team to ensure the design is meeting the specifications.





# Manufacturing data

Gerber files (artwork) and drill files

Documentation for fabrication and assembly (mounting components)  
Creating specific documented highlighting the requirements for fabrication/assembly

# Submitting files for fabrication

Data checked by vendor

Solve engineering queries from vendor on the Gerber files.  
Close issues to start fabrication

# Quality control (QC)

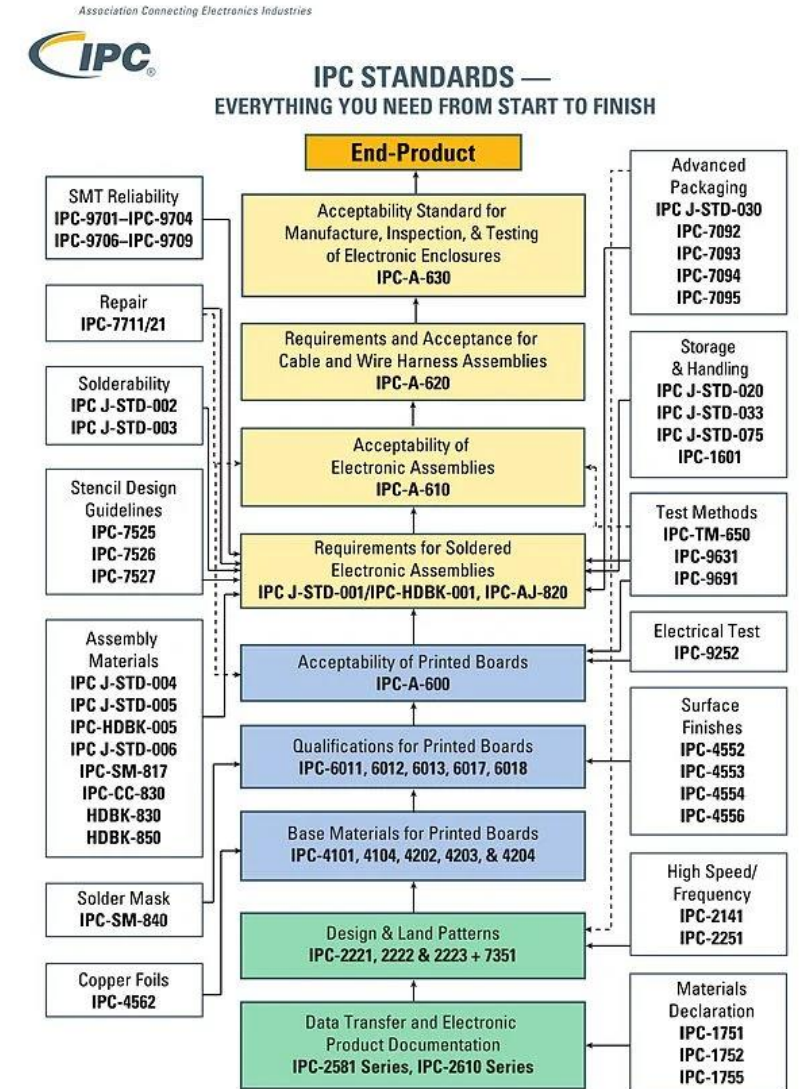
Check to ensure PCBs are fabricated as per specifications

IPC standard are used for PCB manufacturing and assembly

In-house QC tests like visual inspection, layer thickness measurements, etc. based on the application.

# IPC Standards

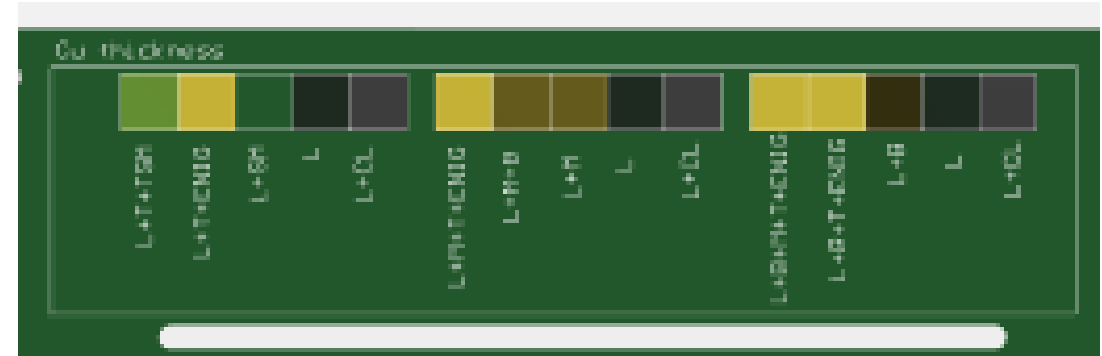
- IPC formerly called the Institute for Printed Circuits, presently called the Association Connecting Electronics Industries standards.
- It is a trade association whose aim is to standardize the assembly and production requirements of electronic equipment and assemblies.
- There is an extensive set of IPC documents that ensure PCB are produced the right way.
- Every step for fabrication and assembly is associated with an IPC standard to carry out the process.
- Similar IPC tests are linked to the assembly process of mounting PCBs with components.
- IPC also defines various testing procedures for testing PCB as a part of QC process .



# In-house QC tests

The QC tests will vary based on application and specifications. Some example tests are-

- **Visual inspection**
  - Check PCBs for contaminations and defects
- **Metrology**
  - Measure size of the PCB, holes etc.
- **Layer stackup check for individual layers**
- **Signal transmission tests**  
(TDR measurements for impedance)
- **Electrical tests to test functionality**





# Conclusion

- PCB designing can vary from a simple single sided design to a complex multilayer design.
- The complexity of PCB layout increases as we –
  - try building products smaller in size and need more circuitry to fit in.
  - work with component packages like BGA, fine pitch connectors etc.
  - work with high-speed signals where timing, noise, impedance become critical.
- Being methodical with PCB layout is very important.
  - Many parameters to consider and adhering to steps helps mitigate errors.
- PCB layout is an important skillset to have when working with electronics and circuit designing.
- In addition to just doing the layout, you gain a good understanding of the overall PCB manufacturing process.

Thank you for listening  
Any questions?